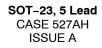




REFERENCE



DATE 09 JUN 2021

NUTES:

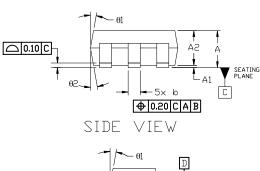
A

F1 F

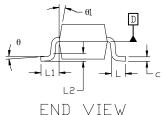
В

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 19894
- CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE RASE MATERIAL
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED O. 25 PER SIDE. D AND E1 DIMENSIONS ARE DETERMINED AT DATUM D.
- 5. DIMENSION '6' DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE '6' DIMENSION AT MAXIMUM MATERIAL CONDITION. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL NOT BE LESS THAN 0.07mm.

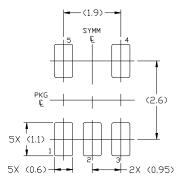
MILLIMETERS



TOP VIEW



DIM MIN. ИПМ. MAX. Α 0.90 1.45 A1 0.00 0.15 Α2 0.90 1.15 1.30 b 0.30 0.50 0.08 0.22 n 2.90 BSC 2.80 BSC E1 1.60 BSC 0.95 BSC е 0.45 0.30 0.60 L1 0.60 REF 0.25 REF L2 4° θ 0° 10° 15° θ1 0° 10° θ2 15°



GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDL DERRM/D.

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|------------------|----------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------|
| DESCRIPTION: | SOT-23, 5 LEAD | | PAGE 1 OF 1 |

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